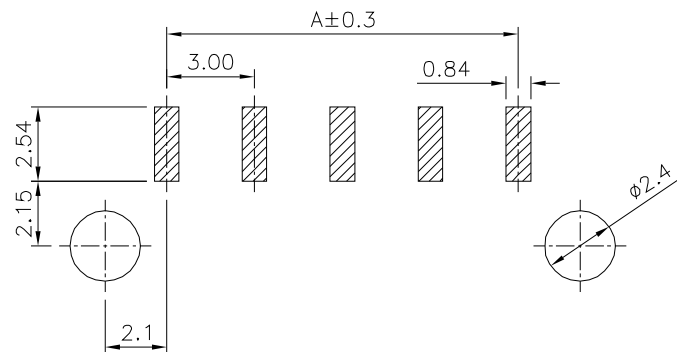
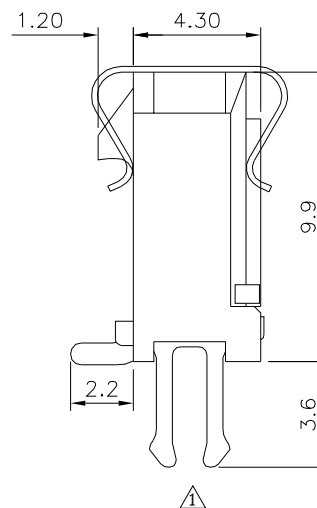
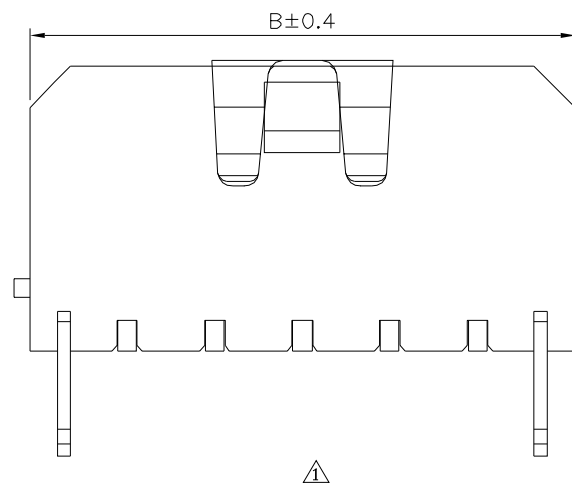
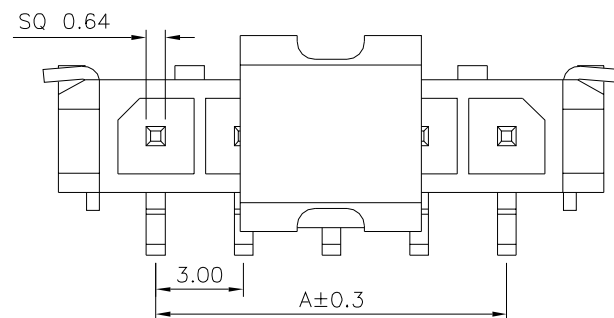




Recommended P.C.B. Layout



SPECIFICATION

1. **General Characteristics**
3.0mm Micro-Fit Wafer 1XXX SMT 180° With
DIP Boardlock Black Insulator Tin Plated With
Cap Tape & Reel 250 PCS/Reel
2. **Material&Finish**
Insulator:LCP(UL94V-0),Black
Contact:Brass,Tin Plated
Press-Fit:Brass,Tin Plated
3. **Electrical Characteristics**
Current Rating:5A AC/DC
Voltage Rating:250V AC/DC
Contact Resistance:10 Milliohms Max.
Insulation Resistance:1000 Megaohms Min.
Withstand Voltage:1500V AC/Minute
4. **Environmental Characteristics**
Temperature Range:-25°C~+85°C
5. **RoHS Compliant**

P _{in}	A	B
02	3.0	9.7
03	6.0	12.7
04	9.0	15.7
05	12.0	18.7
06	15.0	21.7
07	18.0	24.7
08	21.0	27.7
09	24.0	30.7
10	27.0	33.7
11	30.0	36.7
12	33.0	39.7

4UCON 元化興業股份有限公司
4UCON TECHNOLOGY INC.

DRAWING No.

21006

SCALE

NONE

APPROVED BY

MEI

CHECKED BY

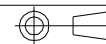
HZF

DRAWING BY

CYP

UNLESS OTHERWISE
SPECIFIED
TOLERANCES ARE
.X ± 0.30
.XX ± 0.20
.XXX ± 0.10
ANG. $\pm 1^\circ$

	UNIT mm
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	A1	Modify Data	HZF	04/19/2017
	A0	NEW RELEASE	HZF	08/23/2015
NO.REV.	REVISIONS		CHK	DATE